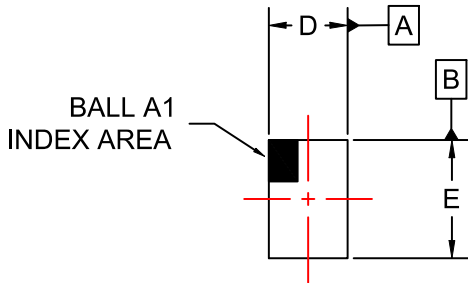
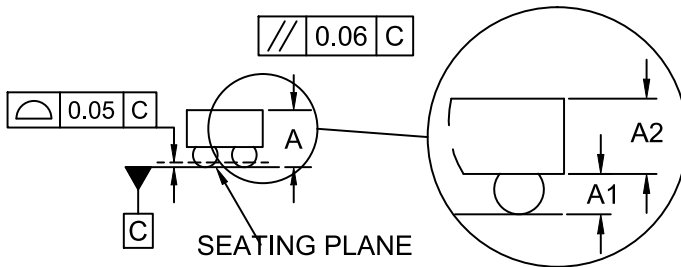


**WLCSP6 1.16x0.86x0.586**  
CASE 567RQ  
ISSUE A

DATE 12 JAN 2018



TOP VIEW



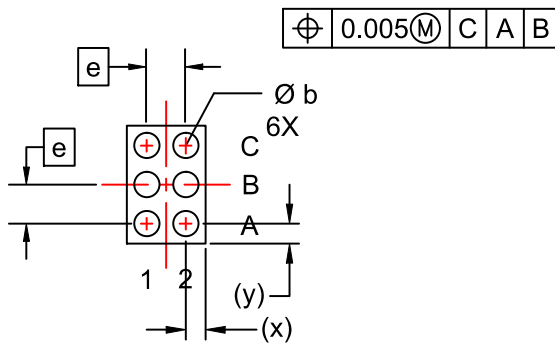
SIDE VIEW

DETAIL A

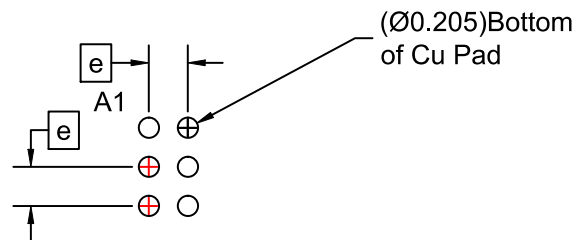
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM			
	MIN.	NOM.	MAX.
A	0.547	0.586	0.625
A1	0.187	0.208	0.229
A2	0.360	0.378	0.396
b	0.240	0.260	0.280
D	0.830	0.860	0.890
E	1.130	1.160	1.190
e	0.40 BSC		
x	0.215	0.230	0.245
y	0.165	0.180	0.195



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT  
(NSMD PAD TYPE)

<b>DOCUMENT NUMBER:</b>	<b>98AON16583G</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>WLCSP6 1.16x0.86x0.586</b>	<b>PAGE 1 OF 1</b>

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.